

# INTT progress report

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# // Ladder assembly progress

All materials were received

Ladder assembly

Half-ladder assembly

Stave ID	Module		assembly date	Bias glue (Y/N)	calibration		
	N	S			done ?	# bad channel	class
"01-0015"	74	262	2021/4/15	Y	Y	2460	5
"01-0060"	51	264	2021/04/28	Y	Y	144	3
"02-0028"	44	pre004	2021/07/28	Y	Y	43	2
"02-0049"	263	48	2021/7/29	Y	Y	0	1
"02-0052"	254	49	2021/8/3	Y	Y	0	1
"02-0046"	255	257	2021/8/5	Y	Y	1	1
"02-0039"	77	78	2021/8/23	Y	Y	2	1
"02-0040"	73	71	2021/8/26	Y	Y	6	1
"02-0019"	53	54	2021/8/27	Y	Y	0	1
"02-0016"	52	55	2021/8/31	Y	Y	3	1
"02-0013"	58	59	2021/09/01	Y	Y	0	1
"02-0001"	253	256	2021/09/02	Y	Y	0	1
"02-0074"	76	261	2021/9/8	Y	Y	63	2
"02-0080"	24	258	2021/9/9	Y	Y	4	1
"02-0077"	57	259	2021/9/13	Y	Y	31	1
"02-0083"	247	246	2021/9/17				
"02-0056"	267	333	2021/12/30				
"02-0065"	349	345	2022/01/06				
"02-0062"	348	341	2022/01/07				
"02-0068"	331	398	2022/01/12				
"01-0104"	350	347	2022/01/13				
"01-0092"	337	346	2022/01/19				

	Total	good	Not yet test
chip to HDI	3	1	2
sensor to HDI	6	4	2
Post-encapsulation	1	1	0
Thermal cycle	16	16	0

16 half-ladders are ready for the ladder assembly

23 ladders have been assembled

**Back up**